

FORM PTO-1449

U.S. DEPARTMENT OF COMMERCE  
PATENT AND TRADEMARK OFFICEATTY. DOCKET NO.  
ELM/001 Cont. 15APPLN. NO.  
10/766,629APPLICANTS  
Glenn J. LeedyCONF. NO.  
3771FILING DATE  
January 27, 2004GROUP ART UNIT  
~~4765~~ 2818SUPPLEMENTAL INFORMATION DISCLOSURE  
STATEMENT BY APPLICANT

## U.S. PATENT DOCUMENTS

EXAMINER INITIAL	DOCUMENT NUMBER	DATE	NAME	CLASS	SUBCLASS	FILING DATE IF APPROPRIATE
JHP	4,500,905	02/19/1985	Shibata	357	68	
	4,939,568	07/03/1990	Kato, et al.	357	75	
	4,892,753	01/09/1990	Wang, et al.	427	579	
	5,000,113	03/19/1991	Wang, et al.	118	723	
	5,240,458	08/31/1993	Linglain, et al.	464	63	
	5,259,247	11/09/1993	Bantien	73	718	
	RE 34,893	04/04/1995	Fujii, et al.	257	419	
	RE 36,623	03/21/2000	Wang, et al.	427	579	
	6,087,284	07/11/2000	Brix, et al.	501	69	
JHP	6,518,073	02/11/2003	Momohara	438	4	12/10/2001

## FOREIGN PATENT DOCUMENTS

EXAMINER INITIAL	DOCUMENT NUMBER	DATE	COUNTRY	CLASS	SUBCLASS	TRANSLATION	
						YES	NO
JHP	04-196,263	07/1992	Japan			(Abs)	

## OTHER DOCUMENTS (Including Author, Title, Date, Pertinent Pages, Etc.)

EXAMINER INITIAL	
JHP	Aboaf, J.A., "Stresses in SiO <sub>2</sub> Films Obtained from the Thermal Decomposition of Tetraethylorthosilicate - Effect of Heat Treatment and Humidity," J. Electrochem. Soc.: Solid State Science; 116(12): 1732-1736 (Dec. 1969).
	Scheuerman, R.J., "Fabrication of Thin Dielectric Films with Low Internal Stresses," J. Vac. Sci. and Tech., 7(1): 143-146 (1970).
	Bailey, R., "Glass for Solid-State Devices: Glass film has low intrinsic compressive stress for isolating active layers of magnetic-bubble and other solid-state devices," NASA Tech Brief (1982).
	"Partitioning Function and Packaging of Integrated Circuits for Physical Security of Data," IBM Technical Disclosure Bulletin, IBM Corp.; 32(1): 46-49 (June 1989).
	Hsieh, et al., "Directional Deposition of Dielectric Silicon Oxide by Plasma Enhanced TEOS Process," 1989 Proceedings, Sixth International IEEE VLSI Multilevel Interconnection Conference, pp. 411-415 (1989).
JHP	Tessier, et al., "An Overview of Dielectric Materials for Multichip Modules," SPE, Electrical & Electronic Div.; (6): 260-269 (1991).

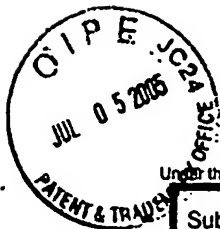
EXAMINER

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EXAMINER: Initial if citation considered, whether or not citation is in conformance with MPEP 609; Draw line through citation if not conformance and not considered. Include copy of this form with next communication to applicant.



PTO/SB/08A (10-01)

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Substitute for form 1449/PTO				<b>Complete if known</b>	
				Application Number	10/766,629 (Conf. No.: 3771)
<b>INFORMATION DISCLOSURE STATEMENT BY APPLICANT</b>				Filing Date	January 27, 2004
				First Named Inventor	Glenn J. Leedy
(use as many sheets as necessary)				Art Unit	2818
				Examiner Name	Thinh T. Nguyen
Sheet	1	of	1	Attorney Docket Number	ELM-1 CONT.15

U.S. PATENT DOCUMENTS					
Examiner Initials*	Cite No. <sup>1</sup>	Document Number	Publication Date MM-DD-YYYY	Name of Patentee or Applicant of Cited Documents	Pages, Columns, Lines, Where Relevant Passages or Relevant Figures Appear
		Number - Kind Code <sup>2</sup> (if known)			
THP		4,724,328	02/09/1988	Lischke	
		4,994,336	02/19/1991	Benecke et al.	
		5,358,909	10/25/1994	Hashiguchi et al.	
		5,514,628	05/07/1996	Enomoto et al.	
THP		5,620,915	04/15/1997	Chen et al.	

FOREIGN PATENT DOCUMENTS						
Examiner Initials*	Cite No. <sup>1</sup>	Foreign Patent Document	Publication Date MM-DD-YYYY	Name of Patentee or Applicant of Cited Documents	Pages, Columns, Lines, Where Relevant Passages or Relevant Figures Appear	T <sup>3</sup>
		Country Code <sup>1</sup> - Number <sup>2</sup> - Kind Code <sup>4</sup>				
THP		GB 2,125,168	02/29/1984	Kouno		
THP		JP 02-037655	02/07/1990	Benecke et al.		

NON PATENT LITERATURE DOCUMENTS			
Examiner Initials*	Cite No. <sup>1</sup>	Include name of the author (in CAPITAL LETTERS), title of the article (when appropriate), title of the item (book, magazine, journal, serial, symposium, catalog, etc.), date, page(s), volume-issue number(s), publisher, city and/or country where published	T <sup>3</sup>
THP		"Christensens Physics of Diagnostic Radiology," Curry et al., pp.29-33, 1990...	

Examiner Signature	THP - THP HCO	Date Considered	Nov 2005
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All References Have Been Considered: \_\_\_\_\_  
Examiner

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